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15th

EMC Compo 2026

International Workshop on the Electromagnetic Compatibility of Integrated Circuits

EMC COMPO 2026
December 7th - 10th, 2026
Okayama Convention Center
Okayama City, Japan

Important Date

Deadline for paper submission	***May 31, 2026***
Notification of acceptance	***Aug. 17, 2026***
Final paper submission	***Sep. 25, 2026***

Organization and venue

Welcome to Japan — the land where tradition meets cutting-edge technology! Following the successful edition held at Torino in 2024, the EMC community will gather again at the Okayama Convention Center, Japan, from Dec. 7th to 10th, 2026, to share the latest advances and exchange ideas on research progress and technological developments in the various topics described below. The 15th International Workshop on Electromagnetic Compatibility of Integrated Circuits (EMC COMPO 2026) is organized by the Institute of Electronics, Information and Communication Engineers (IEICE) and technically co-sponsored by the IEEE EMC Society.

Information for authors

Authors are invited to submit original contributions in two column and either one-page format for abstract submission (in proceedings only) or full-length format for paper submission (for IEEE Xplore Publication) through the online submission system. For full-length papers, the suggested length is between 2 and 4 pages. The paper must follow the IEEE two-column A4 format for Conference Proceedings.

Topics

Topics of interest include, but are not limited to, the following:

- Susceptibility to EMI of analog and mixed signal IPs
- EMC of analog and digital sensors
- EMC of ICs for wireline communications
- EME of core blocks and I/Os
- Substrate coupling in smart power ICs
- Tools to handle EMC at IC and module level
- Measurement methods for chip level EMC
- Materials for improved EMC of ICs
- Influence of IC EMC on system design
- EMC of ICs for biomedical applications
- Power electronics EMC/EMI
- EMC issues in SoC, SiP, and 3D ICs
- EMC-aware Design of ICs and Guidelines
- SI and PI at IC and PCB level
- EMC Standards and regulations
- Long term electromagnetic robustness of ICs

Awards

The Best Paper Award will recognize outstanding academic research in IC EMC. The Best Student Award will be given to a full-length paper whose first and presenting author is a student.

Sponsorship

It is also possible to take advantage of many sponsorship opportunities. Proposals of Diamond Sponsor, Gold Sponsor and Silver Sponsor packages are available, but any form of sponsoring (technical, financial or any other) to promote the workshop is very welcome. To become a conference sponsor please write to contact@emccompo2026.jp.

Organizing committee

General Chair

Makoto Nagata, Kobe University

TPC Chair

Tohlu Matsushima, Kyushu Institute of Technology

Members

Yoshitaka Toyota, Okayama University
Yuichi Hayashi, NAIST
Kengo Iokibe, Okayama University
Kouji Ichikawa, Nagoya Institute of Technology
Hiroshi Suenaga, Panasonic
Koh Watanabe, NICT
Osami Wada, Nagoya Institute of Technology

Tutorials and short courses

Tutorials and short courses will be organized as interactive educational presentations to provide up-to-date practical help to those who are new to the subject or who require an update, as well as to address in-depth topical subjects. For accepted proposals, the tutorial organizer will be responsible for soliciting presentations, corresponding with session speakers, communicating with the Workshop Local Committee, and moderating the session at the workshop. Please send tutorial and short course proposals to contact@emccompo2026.jp by July 31st, 2026.

Contact information

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